



Product Change Notification / JAON-13XUXX883

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**Date:**

03-Mar-2016

**Product Category:**

Capacitive Touch Sensors

**PCN Type:**

Manufacturing Change

**Notification Subject:**

CCB 1582 Final Notice: Qualification of NSEB assembly site for CAP1208 and CAP1298 device families in 16L QFN package using palladium coated copper with gold flash (CuPdAu) bond wire.

**Notification Text:**

**PCN Status:** Final notification

**Microchip Parts Affected:** Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:** Qualification of NSEB assembly site for CAP1208 and CAP1298 device families in 16L QFN package using palladium coated copper with gold flash (CuPdAu) bond wire.

**Pre Change:** Assembled at SCC site using 8290 die attach epoxy, G770 molding compound and matte tin plating.

**Post Change:** Assembled at NSEB using 8600 die attach epoxy, G700LTD molding compound and NiPdAu (PPF) plating.

**Pre and Post Change Summary:**

	<b>Pre Change</b>	<b>Post Change</b>
<b>Assembly Site</b>	SCC assembly site	NSEB assembly site

<b>Wire material</b>	CuPdAu wire	CuPdAu wire
<b>Die attach material</b>	8290	8600
<b>Molding compound material</b>	G770	G700LTD
<b>Lead frame material</b>	C194H	C194
<b>Lead Frame Plating</b>	Matte Sn	NiPdAu (PPF)

**Impacts to Data Sheet:** None

**Reason for Change:** To improve productivity by qualifying NSEB assembly site. SCC assembly site will no longer have manufacturing support to assemble CAP1208 and CAP1298 device families in 16L QFN package. Microchip has qualified NSEB as an alternative assembly site.

**Change Implementation Status:** In Progress

**Estimated First Ship Date:** April 4, 2016 (date code: 1614)

**NOTE:** Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Summary Table:**

WW	April 2015				----->	March 2016					April 2016			
	15	16	17	18		9	10	11	12	13	14	15	16	17
Initial PCN Issue Date			X											
Qual Report Availability						X								
Final PCN Issue Date						X								
Implementation Date											X			

**Markings to Distinguish Revised from Unrevised Devices:** Traceability code

**Revision History:** **April 24, 2015:** Issued initial notification. **March 3, 2016:** Issued final notification. Attached the Qualification Report. Revised the estimated first ship date from October 1, 2015 to April 4, 2016. Added the Pre and Post Change Summary and Summary Table. Updated subject and description of change to inform customers that SCC assembly site will no longer have manufacturing support to assemble CAP1208 and CAP1298 device families in 16L QFN package. These device families will now be assembled at NSEB assembly site.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachments:**

PCN\_JAON-13XUXX883\_Qual\_Report.pdf  
PCN\_JAON-13XUXX883\_Affected\_CPN.pdf  
PCN\_JAON-13XUXX883\_Affected\_CPN.xls

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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